

## RESPONSE TO NOTICE OF NON-COMPLIANCE

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**CLAIMS**

1. (Currently Amended) A thermal transfer device comprising a thermal source maintained in parallel to a thermal sink and having a thermally conductive, compressible, multiple turn coil between the thermal source and the thermal sink.
2. (Previously Presented) The thermal transfer device according to claim 1 wherein the thermal sink surrounds the thermal source.
3. (Previously Presented) The thermal transfer device according to claim 1 wherein said thermal source is made of a dielectric material.
4. (Previously Presented) The thermal transfer device according to claim 1 wherein said thermal source is made of sapphire.
5. (Previously Presented) The thermal transfer device according to claim 1 wherein said thermal sink is made of a dielectric material.
6. (Previously Presented) The thermal transfer device according to claim 1 wherein said thermally conductive coil is made of copper.
7. (Previously Presented) The thermal transfer device according to claim 6 wherein said copper coil is made from copper wire about 0.011 inch thick.
8. (Previously Presented) The thermal transfer device according to claim 1 wherein the thermal source and the thermal sink are concentric.
9. (Previously Presented) The thermal transfer device according to claim 8 wherein a surface of the thermal sink facing the thermal source is grooved to accommodate the compressible coil.

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10. (Previously Presented) The thermal transfer device according to claim 2 wherein the thermal sink includes a means of cooling.

11. (Previously Presented) The thermal transfer device according to claim 1 wherein the conductive, compressible, multiple turn coil fills a space between the thermal source and the thermal sink.

12. (Previously Presented) In a vacuum chamber comprising a processing chamber including a substrate to be processed, and a processing gas inlet source that traverses a microwave energy source for forming a plasma from a processing gas, the improvement comprising:

a microwave impervious gas inlet made of a dielectric material in the form of a tube that provides a thermal source, the dielectric tube surrounded by a concentric dielectric tube that provides a thermal sink, and a compressible, conductive multiple turn coil between the thermal source and the thermal sink.

13. (Previously Presented) The vacuum chamber according to claim 12 wherein said coil is made of copper.

14. (Previously Presented) The vacuum chamber according to claim 12 wherein said gas inlet source is made of sapphire.